XILINX®

PK480 (v1.0) June 17, 2011

100% Material Declaration Data Sheet CS324

Average Weight: 0.545 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					**0.009997**	**1.834**
	Silicon	7440-21-3	100.00	Main material	0.009997	
Die Attach Material					**0.007051**	**1.294**
	Silver	7440-22-4	77.50	Main material	0.005465	
	Bismaleimide monomer	Trade Secret	15.00	Main material	0.001058	
	Acrylate monomer	Trade Secret	7.50	Main material	0.000529	
Gold Wire					**0.006702**	**1.230**
	Gold	7440-57-5	99.05	Main material	0.006638	
	Palladium	7440-05-3	0.95	Dopant	0.000064	
Mold Compound					**0.216990**	**39.815**
	Solid Epoxy Resin	Trade Secret	5.00	Main material	0.010850	
	Phenol Resin	Trade Secret	5.00	Main material	0.010850	
	Fused Silica	60676-86-0	84.45	Filler	0.183248	
	Metal Hydroxide	Trade Secret	5.00	Flame retardant	0.010850	
	Carbon Black	1333-86-4	0.55	Color agent	0.001193	
Solder Balls					**0.096708**	**17.745**
	Tin (Sn)	7440-31-5	63.00	Main material	0.060926	
	Lead (Pb)	7439-92-1	37.00	Main material	0.035782	
Substrate					**0.207552**	**38.083**
	Copper (Cu)	7440-50-8	13.309	Main material	0.027623	
	Nickel (Ni)	7440-02-0	4.696	Main material	0.009747	
	Gold (Au)	7440-57-5	5.606	Main material	0.011635	
	Glass fiber	65997-17-3	19.884	Glass fiber	0.041270	
	Non-Halogen Fire retardant	NA	0.082	Flame retardant	0.000170	
	BT (core)	NA	43.154	Core	0.089567	
	Solder mask	NA	13.269	Solder mask	0.027540	

Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
6/17/11	1.0	Initial Xilinx release.

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